



TSMC Files Annual Report on Form 20-F for 2019

Hsinchu, Taiwan, R.O.C. – April 15, 2020 - TSMC (TWSE: 2330, NYSE: TSM), today filed its 2019 annual report on Form 20-F with the U.S. Securities and Exchange Commission.

The report is available at https://www.tsmc.com/english/investorRelations/sec_filings.htm. Hard copies of the report are also available, free of charge, upon email request to evangelina.sia@citi.com.

ABOUT TSMC

TSMC pioneered the pure-play foundry business model when it was founded in 1987, and has been the world's largest dedicated semiconductor foundry ever since. The Company supports a thriving ecosystem of global customers and partners with the industry's leading process technology and portfolio of design enablement solutions to unleash innovation for the global semiconductor industry.

TSMC serves its customers with global capacity of about 13 million 12-inch equivalent wafers per year in 2020, and provides the broadest range of technologies from 2 micron all the way to foundry's most advanced processes, which is 7-nanometer today. TSMC is the first foundry to provide 7-nanometer production capabilities and the first to commercialize Extreme Ultraviolet (EUV) lithography technology in delivering customer products to market in high volume. TSMC is headquartered in Hsinchu, Taiwan. For more information about TSMC please visit <http://www.tsmc.com>.

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